

2) (Unchanged) Method as claimed in claim 1, wherein the soldering cream (8) is deposited via serigraphy.

3) (Unchanged) Method as claimed in claim 1, wherein the soldering cream (8) is deposited by syringe.

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4) (Amended) Method as claimed in claim 1, wherein it makes it possible to produce an electromagnetic shield (18) integrated directly into the electronic module by conducting connections (19)(21) to the layout (20) of the circuit (3).

5) (Amended) Method as claimed in claim 1, wherein it makes it possible to integrate as close to the connecting balls (7) as possible and on the same side of the electronic module by-pass capacitors (17) and/or series resistors (16) and/or filtering cells and/or quartz adapter condensers.

6) (Amended) Method as claimed in claim 1, wherein the side of the module opposite the side comprising the balls and the components allows gripping of the module by suction.

7) (Amended) Gripping and collective transfer device (9) for balls (7) or geometrically identical preforms, wherein the device has a working face (11) whose configuration is adapted to the dimensions and to the volume of the balls or preforms to be gripped and makes it possible to avoid any contact with the electronic components (2) or any other obstacle that might be present on the surface (12) of the substrate (1).

8) (Unchanged) Device as claimed in claim 7, wherein the gripping device (9) is equipped with a vacuum chamber (13) into which open all of the orifices for holding the balls or preforms (7) in order to seize and place all of said balls simultaneously.

9) (Unchanged) Device as claimed in claim 7, wherein the working face (11) of the gripping device (9) defining the face for holding the balls or preforms (7) is adapted to the dimensions of these balls or preforms and to the shape of the receiver substrate (12).